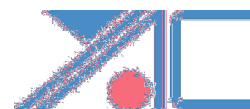




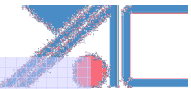
**Financial year ended Mar.31,
2016**

Financial announcement

May. 25, 2016



(Ticker code: 6298)
<http://www.yac.co.jp>



Contents

- 1. Message & summary of business results ended Mar.31, 2016, from president.**
 - **Mr. Takefumi Momose**
Representative Director & President.
- 2. Outline of financial results ended Mar. 31, 2016**
 - **Mr. Kazumasa Teramoto,**
Director & General manager
Administration Div.
- 3. Consolidated business plan for financial year ending Mar.31, 2017.**
 - **Mr. Takefumi Momose,**
Representative Director & president
- 4. Introduction of YAC group's core technologies.**
 - **Mr. Yukio Soejima,**
Director & general manager, Corporate
strategy Div.
- 5. Questions & answers.**



1. Message & summary of business results ended Mar.31, 2016, from president.

**.....Mr. Takefumi Momose,
Representative Director & president.**

1. Summary of financial results



- **Net sales and new order received were historically highest.**
 - **Reorganizes 3 segments increased sales and net sales recorded historically highest.**
 - **Nevertheless operating income increased a bit ordinary income and net income decreased because of foreign currency exchange rate.**

1. Summary of financial results

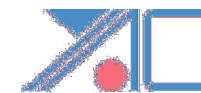


- **Display related business.**
Heating equipment for big, small and medium size panel manufacturing leaded business but some of units of sales squeezed profit.
- **Mechatronics related business.**
Semiconductor and meter for electric power industry went well.
- **Cleaning related and other business.**
Grasping customers' needs and business went well.

2. Outline of financial results ended Mar.31, 2016.

- Mr. kazumasa Teramoto
Director and General Manager,
Administration Div.**

2-1 Business results.

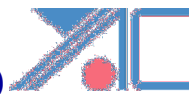


Net sales was 1.5 times of previous year but operating income and net income were decreased because of influence of foreign currency exchange rate.

(Millions of yen)

	Ended Mar.31, 2015.	Ended Mar. 31, 2016.	Increase/(Decrease) against previous year In amount	Increase/(decrease) against previous year in %
Net Sales	16,622	25,545	8,922	53.7%
Operating income (Operating income to sales)	787 (4.7%)	807 (3.2%)	20	2.6%
Ordinary income	966	546	△420	△43.5%
Net income attributable to owners of parent.	639	28	△611	△95.6%
Net income per share.	71.72	3.14	—	—
R&D expenses.	301	328	26	8.9%
New capital investment.	59	147	87	147.1%
Depreciations.	329	450	120	36.6%

2-3 New order received by business segment. (Unofficial figure included.)

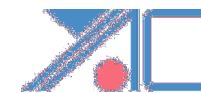


Activity of receiving new order went well in all business segments. Totally 1.7 times of one of the previous year. The one of mechatronics related business segment increased double comparing to previous year.

(Millions of Yen)

	Ended Mar.31, 2015.	Ended Mar. 31, 2016.	Increase/(Decrease) against previous year In amount	Increase/(decrease) against previous year in %
Display related business.	12,811	20,294	7,482	58.4%
Mechatronics related business.	7,110	14,025	6,915	97.3%
Cleaning related and other business.	1,939	2,589	650	33.5%
Total	21,860	36,909	15,048	68.8%

2-2 Net sales by business segment.



Heating equipment for manufacturing of medium and small panel, meter for electric power industry and test handler business went well. YAC Garter which consolidated this year by M&A contributed net sales.

(Millions of yen)

	Ended Mar.31, 2015.	Ended Mar. 31, 2016.	Increase/(Decrease) against previous year In amount	Increase/(decrease) against previous year in %
Display related business.	8,795	14,174	5,378	61.1%
		Heating equipment for manufacturing of medium and small panel went well		
Mechatronics related business.	6,419	9,702	3,282	51.1%
		Meter for electric power industry and test handler went well.		
Cleaning related and other business.	1,407	1,668	261	18.6%
		YAC Garter contributed net sales.		
Total	16,622	25,545	8,922	53.7%

2-3 New order received by business segment. (Unofficial figure included.)



Activity of receiving new order went well in all business segments. Totally 2.6 times of one of the previous year. The one of mechatronics related business segment increased double and display related business increased 4.4 times comparing to previous year.

(Millions of Yen)

	Ended Mar.31, 2015.	Ended Mar. 31, 2016.	Increase/(Decrease) against previous year In amount	Increase/(decrease) against previous year in %
Display related business.	12,811	20,294	7,482	58.4%
Mechatronics related business.	7,110	14,025	6,915	97.3%
Cleaning related and other business.	1,939	2,589	650	33.5%
Total	21,860	36,909	15,048	68.8%

2-4 Backlog ordered by business segment. Unofficial figure included



Obtained the big backlog ordered exceeding previous year end. (Millions of Yen)

	Ended Mar.31, 2015.	Ended Mar. 31, 2016.	Increase/(Decrease) against previous year In amount	Increase/(decrease) against previous year in %
Display related business.	12,192	11,597	△594	△4.9%
Mechatronics related business.	3,204	5,336	2,131	66.5%
Cleaning related and other business.	321	502	181	56.5%
Total	15,718	17,436	1,718	10.9%

2-5 Historical figures of B/S

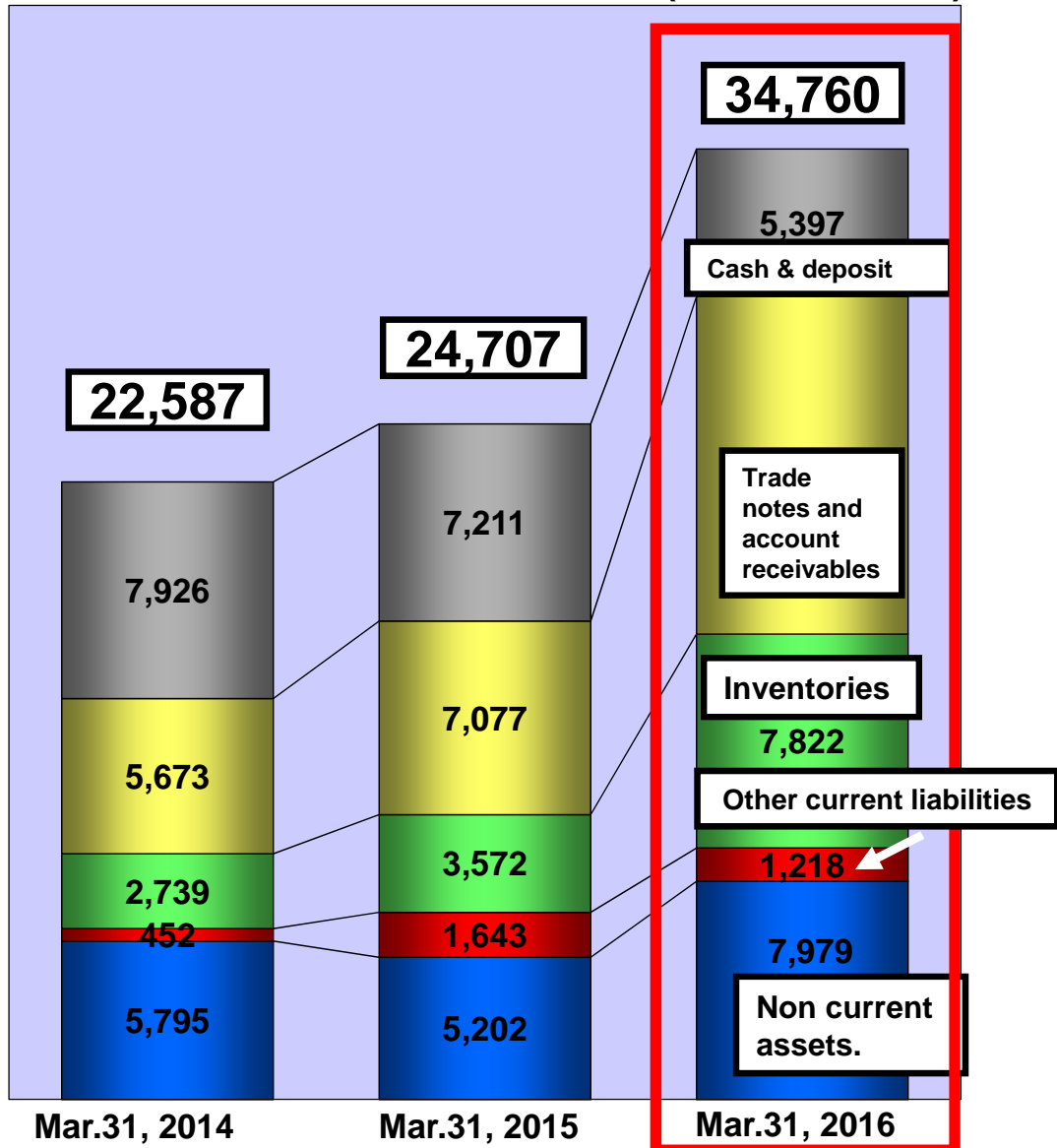


Realization of sales concentrated the 2nd half of year and Trade notes and account receivables increased.

Trade payable increased as well because of big backlog order.

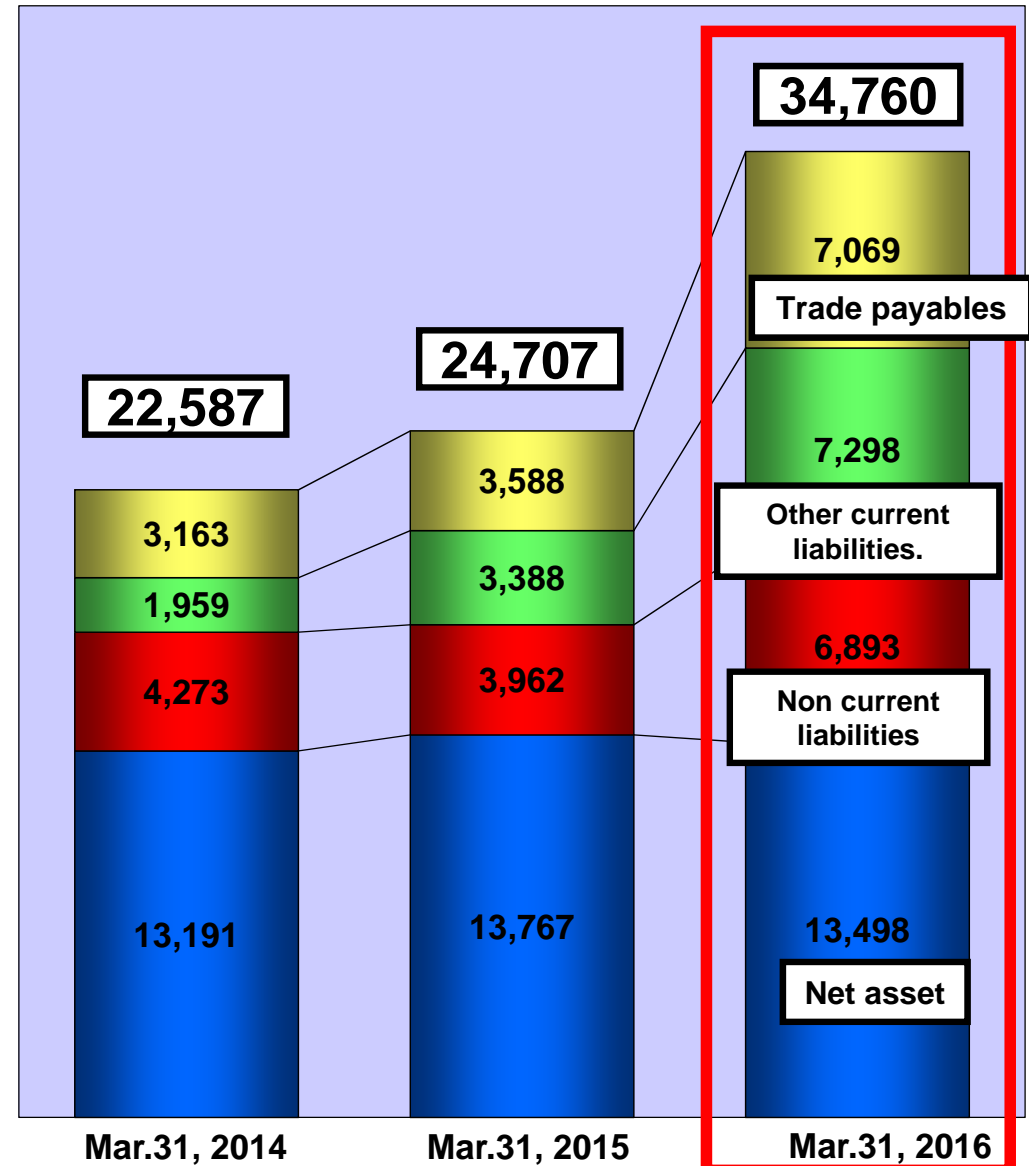
<Assets>

(Millions of Yen)



<Liabilities & Net assets>

(Millions of Yen)



2-6 Summary of cash flow.



Cash flows from operating activities recorded deficit, caused by mainly increased trade note receivables at the end of year. Changes of cash flows with M&A. (Millions of Yen)

	12 month ended Mar.31, 2014	12 month ended Mar.31, 2015	12 month ended Mar.31, 2016
Cash flows from operating activities.	△527	△1,106	△4,715 Caused by big increase of trade note and receivables
Cash flows from investing activities.	△379	△686	△3,862 Caused by acquiring of Nihon Garter and lending.
Cash flows from financing activities.	△177	△502	5,857 Caused by borrowing for M&A.
Cash and cash equivalent balance at end of period.	7,806	7,966	5,155



3. Consolidated business plan for the year ending Mar.31, 2017.

- Mr.Takefumi Momose,
Representative director and
president.**



《Display related business》

Business atmosphere	Priority strategies.
Increasing demand for FPD.	Seeking for synergy effect of dry etching, wet etching and annealing equipment
Increasing demand for new devices.	Focusing for equipment manufacturing of high-definition panel for smart phone and new device processing panel for 4K or 8K TV
Adopting of organic EL panel by Apple.	Introducing new equipment processing of organic EL or flexible panel.
Penetrating low price equipment into market.	Carrying out of cost down projects.

3-1-2 Business atmosphere & priority strategy.



《Mechatronics related business》

Business	Business atmosphere	Priority strategies
Mechatronics	Required higher density HDD.	Receiving new order of capital investment such as advanced HDD applicable to high density.
	Increasing interest for environmental issues.	Promoting new equipment atmosphere related products.
Semiconductor	Increasing electrical equipment in automobile.	Concentrating to receive new order of power semiconductor related investment .
Photo Voltaic	Requiring higher conversion efficiency rate.	Promoting high efficiency panel manufacturing process and products.
Industrial meter, controlling telemetering equipment	Restarted new capital investment because of deregulation of electric power industry and restarted nuclear power generation.	Marketing renewable energy related customers.

3-1-3 Business atmosphere & priority strategy.



《Cleaning related and other business》

Business	Business atmosphere	Priority strategy
Cleaning	Matured domestic market	Introducing new equipment to increase market share.
	Increasing demand from developing countries.	Expanding distributing territory from Asia to North America and Europe.
	Sudden increase of foreign tourists.	Expanding business to linen supply industry.
Mold heater business for automobile.	Heat source of mold heater is changing from gas to electricity.	Providing energy saving and high productivity products which reply to customers' request in automobile and airplane industries.

■ **Net Sales** : **¥30 Billion.**

■ **Ope. income** : **¥1.5 Billion**

◎ Customers' new capital investment is still active.

◎ Backlog ordered is ¥17 Billion as of Mar. 31, 2016.

◎ YAC Garter, which is consolidated from the second half of the financial year ended Mar. 31, 2016 contribute to business results

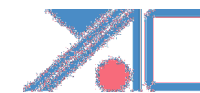
3-3 Forecast of business for the financial year ending Mar.31, 2017



(Millions of Yen)

	12 month ended Mar.31, 2014	12 month ended Mar.31, 2015	12 month ended Mar.31, 2016	12 month ending Mar.31, 2017(forecast)		Increase (decrease) Comparing to the previous year	Increase (decrease) Comparing to the previous year In %
				1 st half	Full year		
Net Sales	14,527	16,622	25,545	13,000	30,000	4,454	17.4%
Operating income	427	787	807	400	1,500	692	85.7%
Ordinary income	546	966	546	350	1,350	803	147.0%
Net income	2,229	639	28	230	890	861	3075.1%
Net income per share.	250.00	71.72	3.14	25.76	99.68	—	—

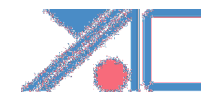
3-4 Sales plan by business.



(Millions of Yen)

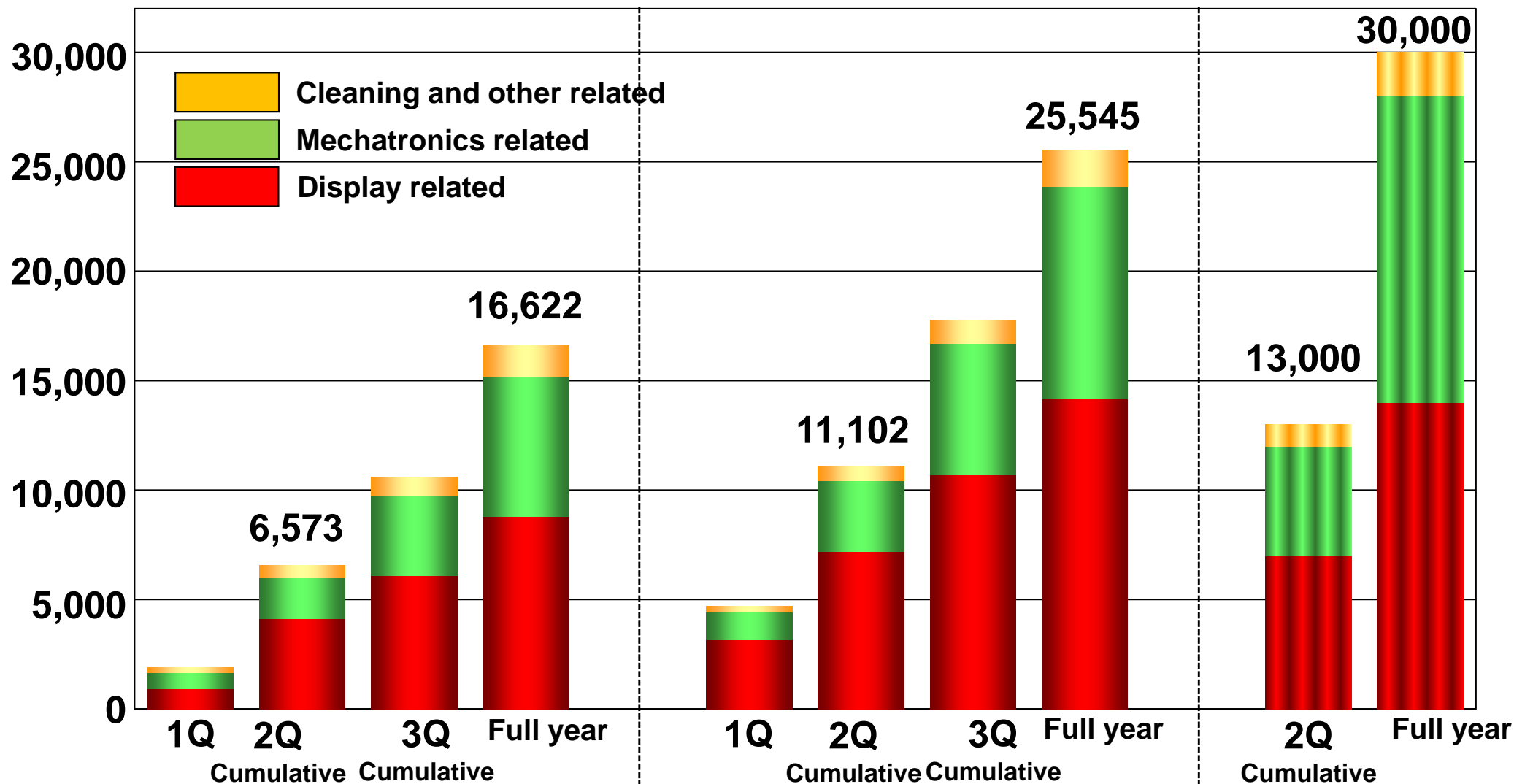
	12 month ended Mar.31, 2014	12 month ended Mar.31, 2015	12 month ended Mar.31, 2016	12 month ending Mar.31, 2017(forecast)		Increase (decrease) Comparing to the previous year	Increase (decrease) Comparing to the previous year In %
				1 st half	Full year		
Display related business.	14,174		11,597	7,000	14,000	△174	△1.2%
Mechatronics related business.	9,702		5,336	5,000	14,000	4,297	44.3%
Cleaning and other related business.	1,668		502	1,000	2,000	331	19.8%
Total	25,545		17,436	13,000	30,000	4,454	17.4%

3-5 Historical figure of net sales.



Net sales

(Millions of Yen)



12 month ended Mar.31,
2015

12 month ended Mar.31,
2016

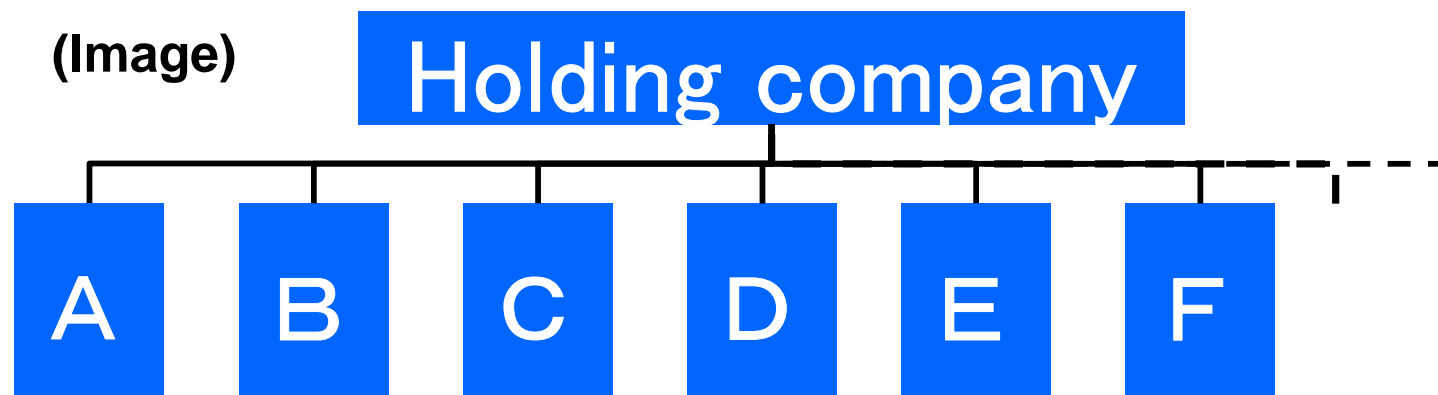
12 month ending
Mar.31, 2017

3-7 Examination of a holding company.



We started to examine to set up a holding company at Apr. 1, 2017 in order to seek for advanced management, increase competitiveness, profitability, and to expand corporate body by aggressive M&A.

We will announce the details when decided after examining.

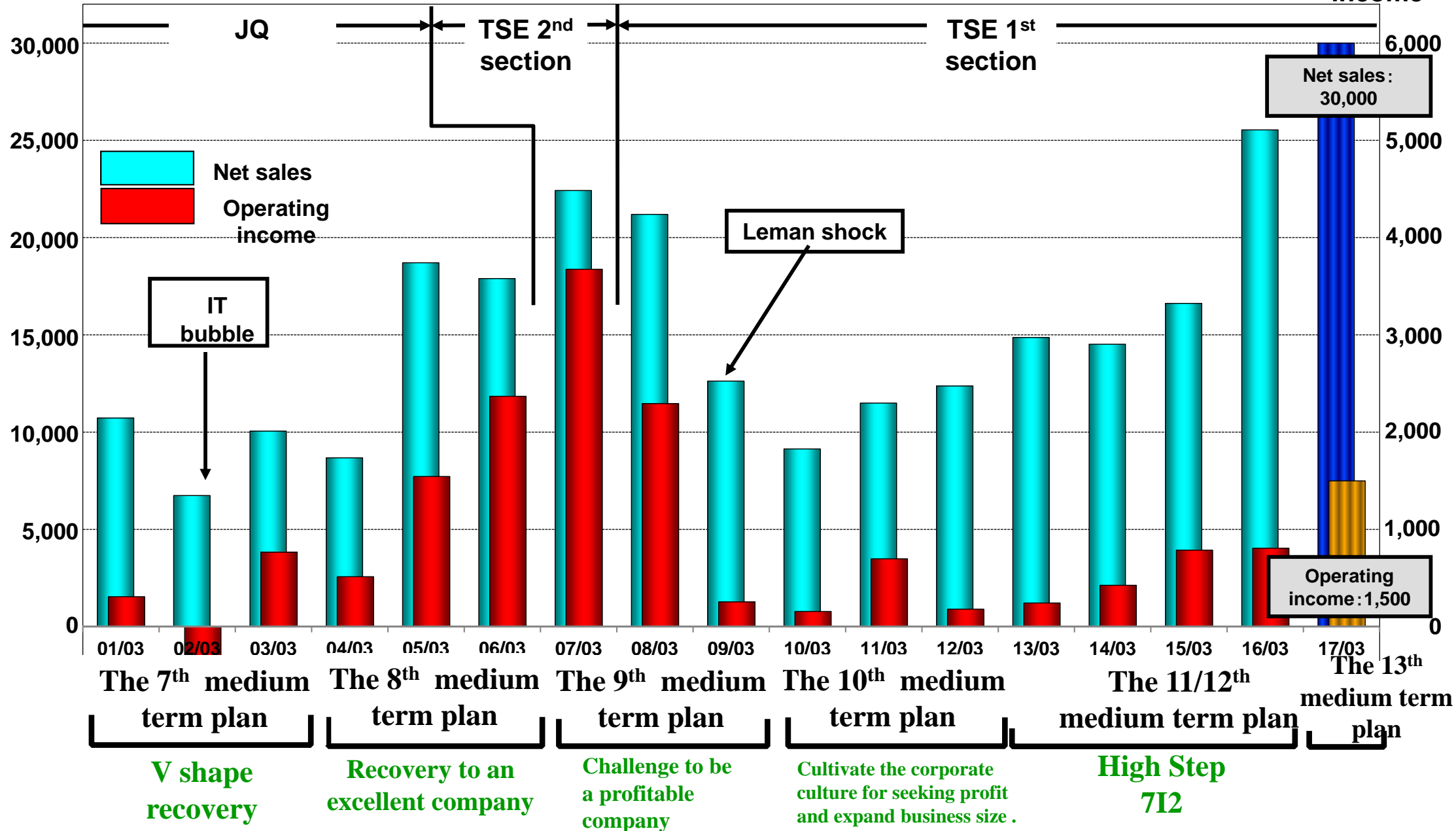


3-8 Past result and forecast of ending Mar.31, 2017



Net sales

(Millions of Yen) **Operating income**





4. Introduction of YAC group's core technologies.

- Mr. Yukio Soejima,
Director and general manager
Corporate strategy Division.**

Organic EL display and YAC group.



Organic EL display is expected to be installed to next generation's smart phone as devices which realize folding display addition to wide view and save electric energy. Since year 2000, we have been shipping organic EL display manufacturing process equipment and present products line are dry etching equipment, wet etching equipment, annealing equipment and baking equipment.

From now on, folding flexible organic EL panel will be required much more and our high technology equipment such as heat treatment and etching will be necessary much more. Heat treatment technology which is used for oxide semiconductor is applied to manufacture low frequency drive hybrid circuit such as LTPO and LTPS. Precise etching technology is applied to form vapor deposition mask which is necessary for high definition.



Dry etching equipment



Wet etching equipment



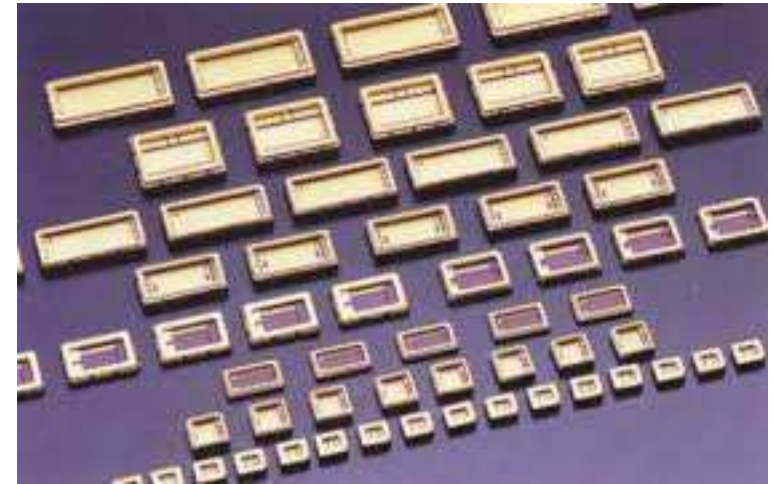
Annealing equipment

Our technology support manufacturing process of organic EL display.

Cutting equipment of multilayer ceramic package.



Internet data volume is tremendously increasing by IoT devices, smart phone and tablet PC and communication volume is increasing at wireless communication base station. Multilayer ceramic package which install small electronics devices such as crystal devices, SAW filter and high frequency devices.




Source: Japan ceramic association museum

Multilayer ceramic package is manufactured by cutting 5mm thick solid high temperature alumina ceramic using our DAS110 cutter. Characteristic of DAS110 cutter is applicable to cut solid thick ceramic material by thin blade with installing high power spindle to high rigidity housing. A large number of customers use high productivity particular automatic alignment function controlled by specific software which is applicable to ceramic package size distortion caused by thermal contraction.



DAS101cutter

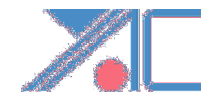
We support manufacturing of ceramic package which spread to automobile, medical equipment and power semiconductor by cutting technology.

A decorative banner at the top of the slide features a collage of images: a golden mechanical part, a grid of solar panels, a view of the aurora borealis, a bright sun flare, a field of solar panels under a blue sky, and a person in a white lab coat working in a laboratory.

Attachment Corporate outline

- 1. Basic information.**
- 2. Special features of Y.A.C. Co., Ltd.**
- 3. Global network of YAC group.**
- 4. Group companies.**
- 5. Major products.**

1. Basic information



C o r p o r a t e N a m e	Y.A.C. Co., Ltd.
T i c k e r c o d e	6298 (TSE 1 st section)
E s t a b l i s h e d	May, 1973
R e p r e s e n t a t i v e	Takefumi Momose, President
O f f i c e s	Head Quarter:3-11-10 Musashino, Akishima, Tokyo Japan Sales Office :Osaka, Akishima, Shinchu (Taiwan) Factories :Akishima, Yamanashi, Kumamoto, Ohita
G r o u p C o m p a n i e s (c o n s o l i d a t e d)	Ohkura Electric Co., Ltd.(Sakato, saitama Pre.) YAC Denko Co., Ltd. (Ohme, Tokyo) YAC Niigataseiki Co., Ltd. (Myukou, Niigata Pre.) YAC DAStech, Inc.(Toda, Saitama Pre.) Y.A.C. Kokusaidennetsu Co., Ltd(Musashimurayama, Tokyo) YAC Garter Co., Ltd. (Ohme, Tokyo) YAC Systems Singapore Pte. Lt. (Singapore) YAC (Shanghai) International Trade Co., Ltd. (Shanghai, PRC) Shaoxing YAC(Shanghai) Electronic Equipment Co., Ltd. T.Y.A.C. Corp.
P a i d u p C a p i t a l	¥2,756million
M a j o r P r o d u c t s a n d s e r v i c e s	Developing, Drawing, Manufacturing & Selling of Manufacturing Equipment for Display related equipment, Mechatronics related equipment and Cleaning related equipment.
A c c o u n t C l o s i n g	March 31

2. Special Features of YAC Co., Ltd.



- **Previous year, adding 1 business and diversified various fields.**
- **Fables management.**
- **Challenging for M&A, acquired 12 business during past 15 years.**
- **Global enterprise focusing Asia.**



■ **Penetrating into device business.**

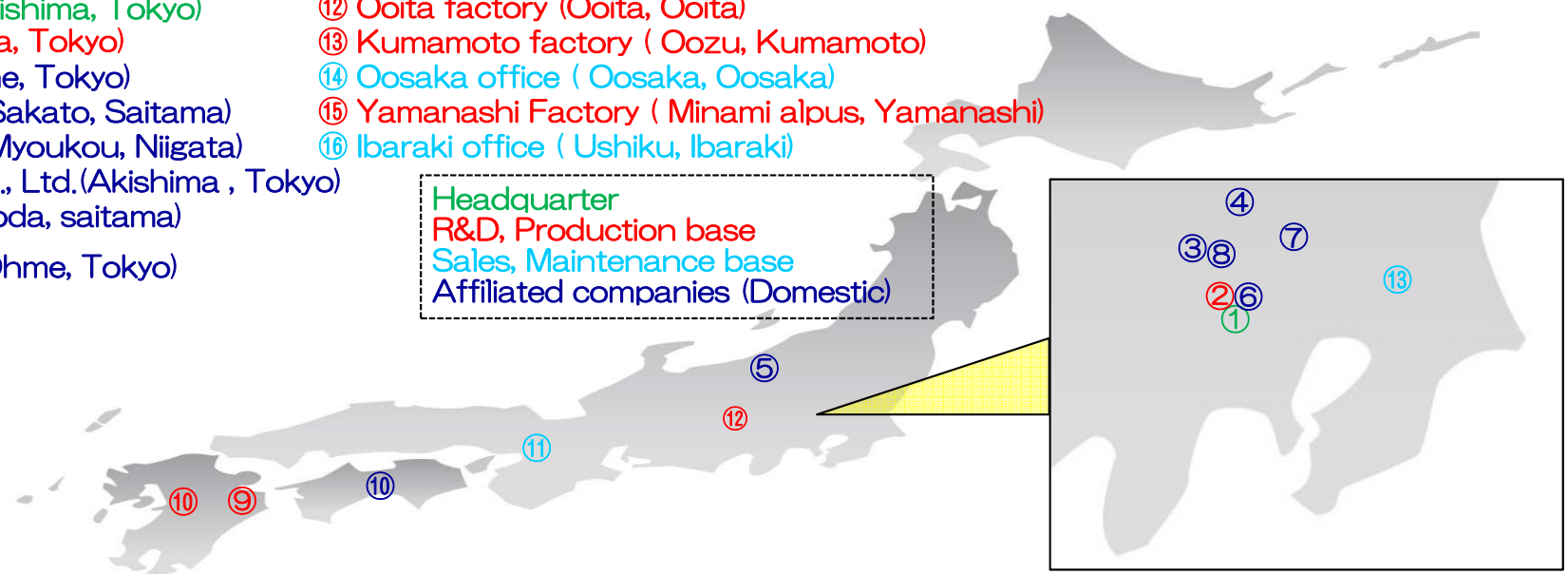
■ **All-in-one management with employee.**

3. Global network



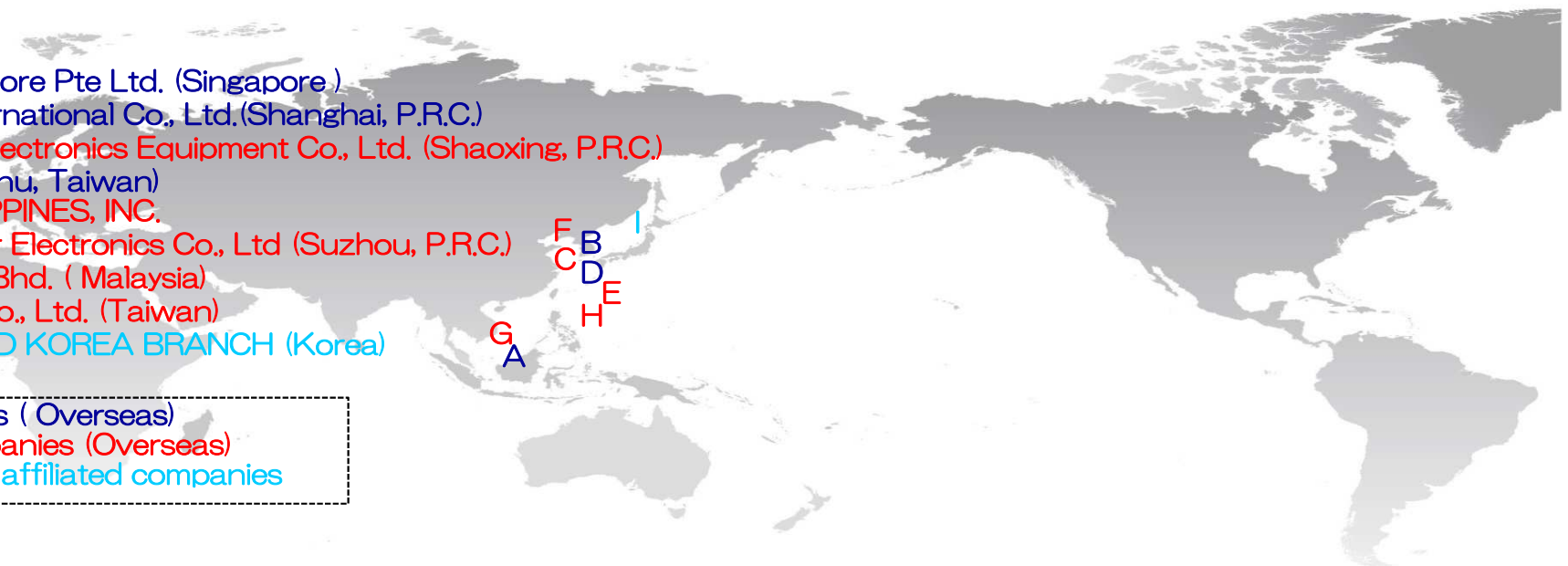
- ① Head Quarter/ Factory (Akishima, Tokyo)
- ② Technical Center (Akishima, Tokyo)
- ③ YAC Denko Co., Ltd. (Ohme, Tokyo)
- ④ Ohkura Electric Co., Ltd. (Sakato, Saitama)
- ⑤ YAC Niigata Seiki Co., Ltd. (Myoukou, Niigata)
- ⑥ YAC-Kokusaidennetsu Co., Ltd. (Akishima, Tokyo)
- ⑦ YAC DASTech Co., Ltd. (Toda, Saitama)
- ⑧ YACGARTER CO., LTD. (Ohme, Tokyo)

- ⑫ Ooita factory (Ooita, Ooita)
- ⑬ Kumamoto factory (Oozu, Kumamoto)
- ⑭ Oosaka office (Oosaka, Oosaka)
- ⑮ Yamanashi Factory (Minami alpus, Yamanashi)
- ⑯ Ibaraki office (Ushiku, Ibaraki)



- A) YAC Systems Singapore Pte Ltd. (Singapore)
- B) YAC (Shanghai) International Co., Ltd. (Shanghai, P.R.C.)
- C) Shaoxing Weiaixin Electronics Equipment Co., Ltd. (Shaoxing, P.R.C.)
- D) T.Y.A.C. Corp. (Hsinchu, Taiwan)
- E) YAC GARTER PHILIPPINES, INC.
- F) Suzhou Nihon Garter Electronics Co., Ltd (Suzhou, P.R.C.)
- G) NGC Garter (M) Sdn. Bhd. (Malaysia)
- H) Garter Technology Co., Ltd. (Taiwan)
- I) YACGARTER CO., LTD KOREA BRANCH (Korea)

Affiliated companies (Overseas)
 Sub-affiliated companies (Overseas)
 Overseas branch of affiliated companies



4. Group companies



In Japan

■ Y.A.C. Co., Ltd.

Mechatronics Products Div.
Display Manufacturing Equipment Div.
Cleaning Equipment Div.

■ 6 Group companies.

YAC Denko Co., Ltd.	Ohme, Tokyo
Ohkura Electric Co., Ltd.	Sakato, Saitama
YAC Niigata Seiki Co., Ltd.	Myoukou, Niigata
YAC DASTech co., Ltd.	Toda, Saitama
YAC-Kokusaidennetsu Co., Ltd.	Akishima, Tokyo
YAC GARTER CO., LTD.	Ohme, Tokyo

Outside of Japan

■ 3 Group Companies

YAC Systems Singapore Pte Ltd.	Singapore
Y.A.C. (Shanghai) International Trade Co., Ltd.	Shanghai, P.R.C.
T.Y.A.C. CORP.	Hsinchu,

■ 5 sub-subsidiaries and 1 branch

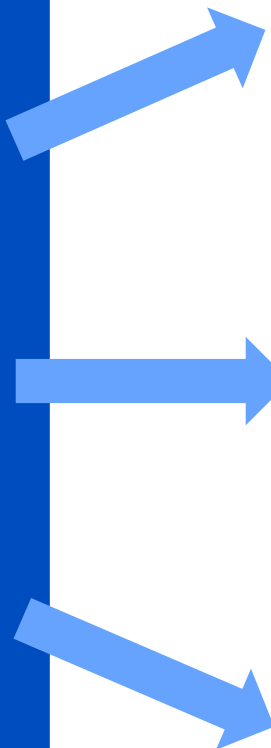
Shaoxing Weiaixin Electronic Equipment Co., Ltd.	Shaoxing, P.R.C.
NIHON GARTER PHILIPPINES, INC.	Philippines
Suzhou Nihon Garter Electronics Co., Ltd.	Suzhou, P.R.C.
NGC Garter(M) Sdn. Bhd.	Malaysia
GARTER TECHNOLOGY CO., LTD.	Taiwan
YAC GARTER CO.,LTD KOREA BRANCH	Korea

4 business divisions, 6 domestic group companies, 3 overseas group companies and 5 overseas sub-subsidiaries.

5-1 Major clients



YAC Group manufacturing and selling mainly automation equipment.



Major clients	Major products
Panel display manufacturer.	Plasma etching equipment, wet etching equipment and heat treatment equipment.
Hard Disk manufacturer.	Burnisher and UV cure equipment.
Semiconductor manufacturer.	Test handler, clean conveyer, slicing and dicing machine, laser annealing equipment and carrier tape.
Solar panel manufacturer.	Texturing equipment ISO-PSG equipment.
Power company.	Industrial metering equipment, telemetering and controlling equipment.
Automobile and air craft manufacturer.	Heating equipment.
Cleaning business.	Finisher for shirts, finisher for suit and automated bagging machine.

5-2 Features of major products



Products	Features
Burnishing equipment for HDD.	Only one company in the world. Continuous demand is expected following by high recoding density of HDD.
Plasma etching equipment	Very competitive in the panel manufactures for smartphone and tablet and market share is No.1 in the world.
Cleaning equipment	Number 1 domestic market share holder of Finisher for shirts and Bagging equipment.



Burnishing equipment for HDD



Plasma etching equipment

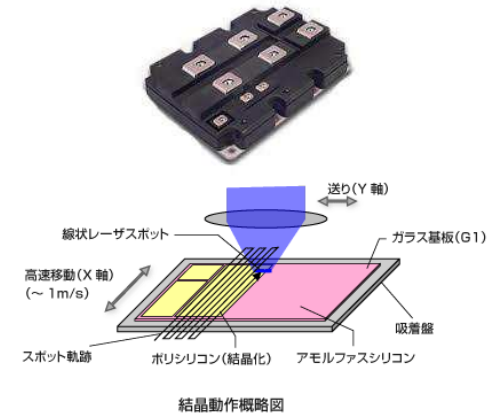
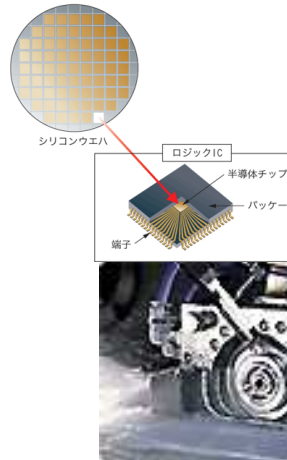


Automated bagging equipment.

5-3 Core technologies

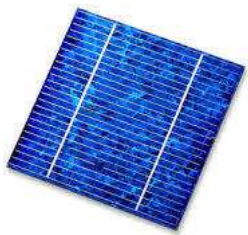


■半導体素子の構造



— Plasma, Vacuum and Heat —
Etching, Reforming and Diffusion

— Cutting, Laser —
Dicing and Diffusion



— WET —
Etching and Texturing

— Handling —
Handler and Conveyer

— Precise polishing —
Burnisher

5-4 LCD related business



Plasma dry etching equipment	Dry etching equipment by using plasma technology. The most suitable for high definition panel manufacturing such as LTPS and OLED for smart phone , efficient manufacturing process and mask less technology.
Annealing equipment	Heat treatment equipment (RTA) for reforming and improving film quality. Suitable for mass production of high definition panel such as LTPS and contributed for high functionality of smart phone and tablet.
Wet etching equipment	Wet etching equipment using chemical liquid. Applying for small to large panel including high definition panel such as IGZO, OLED and metal wiring.



Plasma dry etching equipment



Annealing equipment



Wet etching equipment

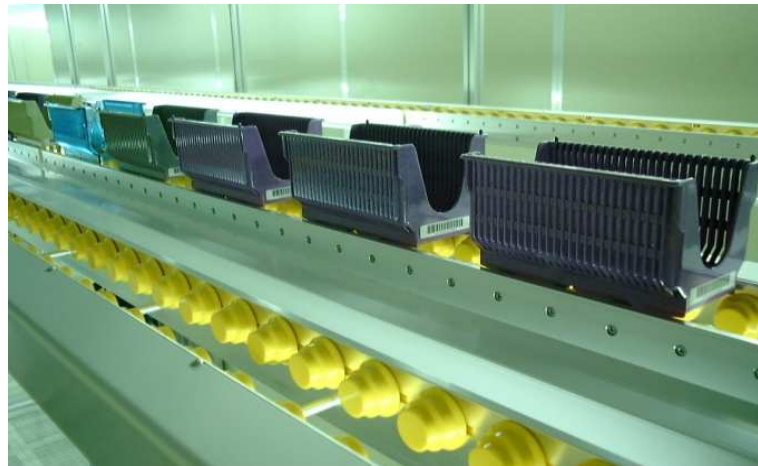
5-5 Hard disk related business



Banisher for HDD	The disk surface precise polishing equipment to eliminate the nano-size projections on the disk surface after the process of magnetic film generating.
Wiping System for HDD	The equipment to remove particles on the disk surface and to equalize the lubricant agent after the process of magnetic film generating.
UV Curing	UV Curing Surface-reforming for Hard Disk
Clean Conveyor	<p>For HDD factory: Possible to built various type of transportation line easily by module combination.</p> <p>For semiconductor factory: Achieved high load-bearing performance, impact performance and speed performance for 300 mm wafer pot.</p> <p>Solar sells factory: Transport big size substrate with high load-bearing performance and impact performance.</p>



Banisher



Clean conveyor for hard disk



High speed clean conveyor for semiconductor

5-6-1. Semiconductor testing & cleaning related.



Testing handler.	Equipment that screen automatically good or bad after packaging of logic IC. Applicable wide range of temperature between 55 degree C. to 155 degree C.
Semiconductor and parts cleaning equipment.	<ul style="list-style-type: none">•Wet process equipment: Cleaning equipment, resist removal equipment and night ride equipment.•Semiconductor peripheral equipment: Quarts tube cleaner, stocker and chemical liquid supplying equipment.
IPA vapor dryer.	Drying wafer by using IPA vapor at the final stage of semiconductor, including LSI, MEMS, and power devices, cleaning process with free from particles.



Test handler for logic IC.



Quarts tube cleaner



IPA vapor dryer

5-6-2. Semiconductor laser process related.



Laser anneal machine

- Laser anneal equipment for IGBT and power semiconductor
 - Heat only on backside by 2 wavelength laser anneal and control anneal depth from 1 to 10 micro mater.
 - High throughput was realized by combination of continuously oscillating laser and turn table.
- Backside Laser Annealing System for Ohmic Contact Formation on SiC.
 - The 1st time equipment in the world and applicable development and prototype of products.
 - This equipment will support mas production by its high stability, reproducibility, throughput and low running cost.
- Laser scriber.
 - Exclusive use for SiC and realized debris less.

Micro multi laser drilling machine

- Ultra precise hole making : Making diameter 15 to 50 micrometer hole.
- High speed great number holes making : Making maximum diameter 100 mill meter and maximum number one million holes by 30 to 500 seconds. (less than 0.1 mill second/hole)
- Precise hole making: Hole position accuracy <0.5micro meter hole diameter accuracy <0.5 micro meter.
- Long term stability, easy control and less downtime:
 - Unaffected from change of razor profile.
 - Easy control because of simple optical system.



Laser anneal machine for IGBT and power semiconductor



Backside Laser Annealing System for Ohmic Contact Formation on SiC



Micro multi laser drilling machine

5-6-3. Semiconductor precise dicing and slicing related.

Full automated slicer	This is a full automatic slicer to cut thick or complex device which have realized to cut device by one pass in stead of step cut even device that old fashioned slicer used to cut by step cut. For: Complex devices such as devices containing sapphire, glass, ceramic and packaged devices such as CSP, QFP, QFN and metallic devices.
Slicing and dicing machine	Automatic θ -AXIS, having automatic alignment function. Possible to cut thick device highly precisely by multi blade.
Full automated core drilling machine	This is full automatic drilling machine which cut the subject such as glass or quarts into circle shape or donuts shape by using core drill. This machine has auto transport and automatic alignment functions . Recently we introduced new equipment DAR806 which is applicable to smaller diameter (1to 10) with ultra sonic spindle
Resale business	We purchase, repair and resell secondhand dicing equipment, cutting equipment and semiconductor manufacturing equipment. <div style="border: 1px solid black; padding: 10px; margin-top: 10px;"> <p style="text-align: center;">ダイサー再生・販売ステーションのしくみ (全て自社にてご提供)</p> </div>



DFS1100

Full automatic slicer



DAS110

Slicing/Dicing



DAR806

Automatic core drilling machine



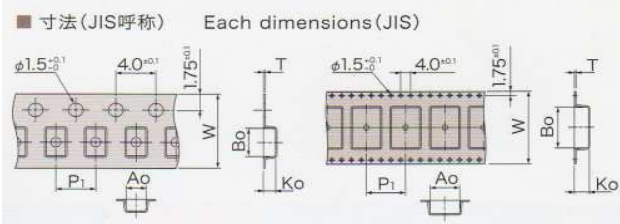
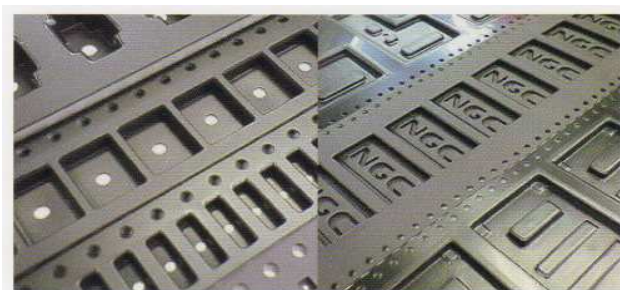
DAR810

Full automatic core drilling machine

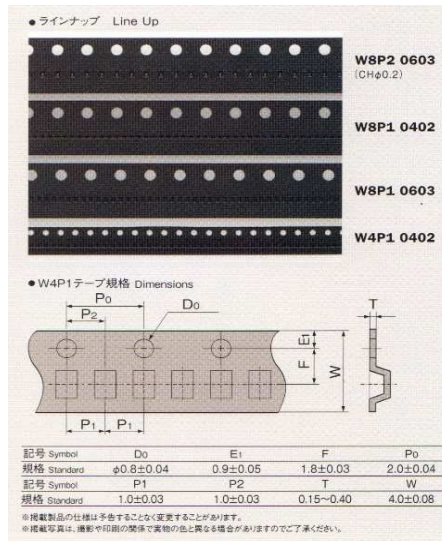
5-6-4. Semiconductor embossed carrier tape related.



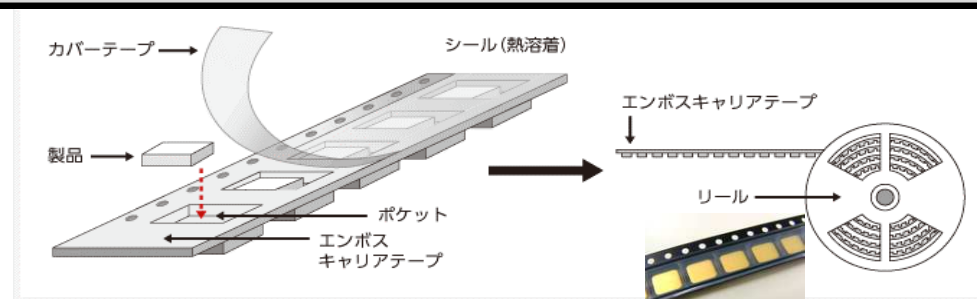
Embossed carrier tape	Packaging material for mounting of surface-mount electronic components such as condenser diode, transistor, semiconductor and LED by using automatic mounting machine.
Ultra micro and thin embossed tape	Embossed carrier tape for small (0.2 mm x 0.1 mm) and thin products (less 0.1 mm thin).
Service business	Taping service business for prototype or small lot products of electronic components by embossed carrier tape including vacuum packaging.
Peeling tester	Testing equipment for setting peel strength of sealed cover tape on emboss carrier tape properly.
Auto reel changer	Continuous operating machine which changes embossed carrier tape reel automatically, raise machine utilization and contribute for laborsaving.



Embossed carrier tape



Ultra micro and thin embossed tape



Taping service



Peeling tester



Auto reel changer

5-6-5. Semiconductor LED & Electronics related.



LED classifier	Classifying bulk of LED after dicing process into maximum 256 groups by optical inspection and electrical characteristic test.
Taping machine	Inserting, sealing with heat and packaging classified bulk LED and electronics parts with inspecting energization, line up in one direction.
Sheet taping machine	Peeling off semiconductor or LED wafer from sheet after dicing process and inserting, sealing with heat and packaging classified bulk LED and electronics parts with inspecting energization, line up in one direction.
LED measuring machine	Mounted on LED classifier or inspecting taping machine and doing optical inspection and electrical characteristic test of LED and transmit the result to classifier or inspecting taping machine
LED alliance	We organize a LED alliance aiming to LED new market such as India and Vietnam with major LED manufacturing equipment and element makers such as Canon machinery, Musashi engineering TOWA, Toyota Gosei, Panasonic, Shin-Etsu Chemical, and Kanematsu and support new markets.



LED Classifier



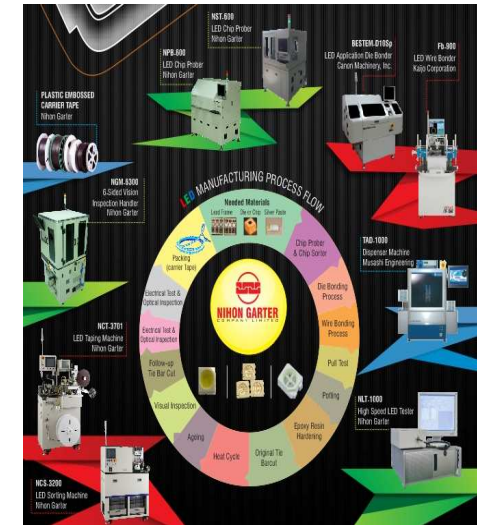
Taping machine



Sheet taping machine



LED Measuring machine



LED Alliance

5-7 Photovoltaic related business.



Wet equipment for manufacturing of crystalline silicon solar cells

Butch type texturing machine
Butch type and inline type isolation equipment and PSG etching equipment
Plating type wiring equipment

Various type of heat treatment equipment

Vertical glass substrate heating equipment.
Eva cross linkage furnace for thin film solar cell.
Vertical multistage diffusion furnace
Walking beam continuous drying furnace
Tube diffusion furnace



Texturing equipment



ISO/PSG



Cure/Anneal furnace

5-8 Cleaning related business



Dress shirt pressing machines	<p>Pressing machine by using heated panel and hot air. Standard type of product functions are diversified into 3 unit such as for pressing collar & cuff, tuck & sleeve and body, but operating speed are rapid. We have another type of product which can press tuck & sleeve and body by one unit so called Body sleeve type.</p>
Wool finishers	<p>pressing equipment for jacket and pants</p>
Bagging machines	<p>The machine to bag automatically the finished item we have two type of machine, one is to bag items with dress hanger another is to bag by folding.</p>
Apparel equipment	<p>We have various type of machines which are used in the production line of making apparel such as sponging machine, fusing machine and pressing machine</p>



Body-sleeve pressing machine for dress shirts



Finisher for jacket

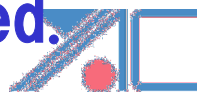


Finisher for pants



Bagging machine (Dress hanger type)

5-9. Precise heating treatment, FPD, electronics and automobile related.



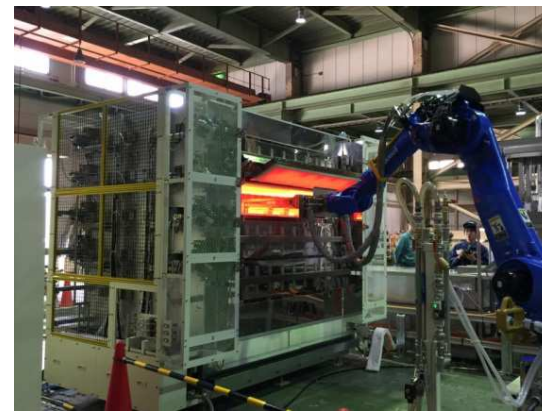
<p>Heating equipment for Flat Panel Display (FTP)</p>	<p>Heating equipment for LCD panel manufacturing: MB/MS series Heating equipment for LCD and OLED panel manufacturing: MT series Hot plate type heating equipment for LCD panel manufacturing Decompression type drying equipment for LCD and OLED panel and Walking Beam type consecutive heating treatment furnace</p>
<p>Heating Furnace equipment for precision parts</p>	<p>Consecutive muffle kiln with mesh belt conveyor (Muffle), consecutive muffles kiln with mesh belt conveyor (Muffles) and various type of testing kiln for electronics parts.</p>
<p>Heater and other related equipment</p>	<p>Radiant pat heater (PD/GPD) Infrastructure unit (BD/SG) Infrastructure unit heater (PS/PU/PH/PM) another industrial heaters.</p>
<p>Heater for automobile parts</p>	<p>Furnace for automobile industry (High tension sheet steel tempering equipment) Furnace for molding and pre-heater for molding</p>



Annealing equipment for IGZO/OLED



Consecutive muffle kiln with mesh belt conveyor



Tempering equipment for automobile high tension sheet steel.

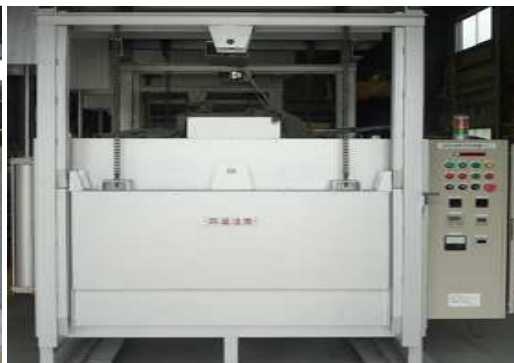


5-10 Precise heating treatment, molding and industrial furnace related.

<p>Mold heater for forging and casting</p>	<p>Die heater, DH series. Mold heater for hot forging and warm forging.</p>
<p>Industrial furnace, heat treatment equipment</p>	<p>Bogie hearth furnace, T5 T6 heat treatment furnace, Mold heater, Hardening furnace and Pit furnace.</p>
<p>Large forging heat treatment equipment for aircraft.</p>	<p>High temperature mold preheater</p>
<p>High speed heater</p>	<p>Heater for automobile power train.</p>



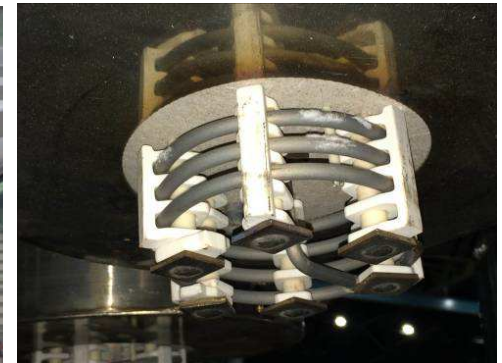
Mold heater for forging and casting



Industrial furnace heat treatment



Large forging heat treatment equipment for aircraft

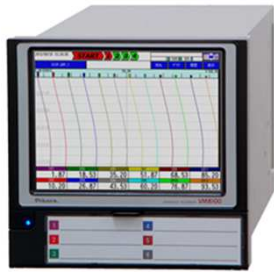


High speed heater

5-11. Industrial metering and telemetering and controlling related business.



Industrial metering equipment	Utilizing metering and controlling technology, we have been contributing to wide range industrial automation from recorder and data processing systems for atomic power plant, precise temperature controlling system to environmental analytical sensor.
Telemetering controlling equipment	We have been contributing to building of social infrastructures with providing information transmitter, distance controlling monitoring system, data processing system as well as precise electric power meter and modem in order to support huge and wide range network of electricity system, city gas providing system, water and sewerage system and railway system.
Semiconductor	We have been providing vertical and horizontal diffusion furnace, diffusion controlling system as well as furnace renewal service by using own metering , controlling and censing technology cultivated as industrial metering manufacturer.



Paperless recorder



Digital indicating controller

Programing controller



High bride controller



Pressure transmitter



IP-enabled information transmitter



IP-enabled information input output device



High precision transducer



Vertical diffusion furnace
Semiconductor manufacturing equipment

Industrial metering equipment

Telemetering and controlling equipment



Well, Today should be

a Fascinating and Prosperous Day, again!

Flexible High-Technology Company



Y.A.C. Co., Ltd.

The prospects described in this document is based on the information we have as of the time this document is published, and the actual result may differ from such prospects due to various unexpected factors.